

Title (en)

METHODS AND APPARATUS FOR PROCESSING A SUBSTRATE

Title (de)

VERFAHREN UND VORRICHTUNG ZUR VERARBEITUNG EINES SUBSTRATS

Title (fr)

PROCÉDÉ ET DISPOSITIF DE TRAITEMENT D'UN SUBSTRAT

Publication

EP 1976806 A2 20081008 (EN)

Application

EP 06844980 A 20061207

Priority

- US 2006046765 W 20061207
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Abstract (en)

[origin: WO2007070353A2] Apparatus and methods adapted to polish an edge of a substrate include a polishing film, a frame adapted to tension and load the polishing film so that at least a portion of the film is supported in a plane, and a substrate rotation driver adapted to rotate a substrate against the plane of the polishing film such that the polishing film is adapted to apply force to the substrate, contour to an edge of the substrate, the edge including at least an outer edge and a first bevel, and polish the outer edge and the first bevel as the substrate is rotated. Numerous other aspects are provided.

IPC 8 full level

C03C 15/00 (2006.01)

CPC (source: EP KR)

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